

Title of Change:	Qualification of ON Semiconductor Gresham, Oregon as an additional wafer fab location (I3T80U technology),currently manufactured in Fab2, Oudenaarde, Belgium, and the qualification of AMKOR P1, Philippines, as an additional assembly location (36Id SSOP), currently manufactured in OSPI, Philippines, for the NCV78763DQ6R2G product.		
Proposed first ship date:	31 August 2017 or earlier upon customer approval		
Contact information:	Contact your local ON Semiconductor Sales Office or Customer Quality interface		
Samples:	Contact your local ON Semiconductor Sales Office or Customer Quality interface		
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 12 months prior to implementation of the change. In case of questions, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>		
Change Part Identification:	The OPN and the part marking will be updated:		
	Current OPN: NCV78763DQ6R2G (Fab2 + OSPI)		
	Dual Fab and Assembly Source OPN: NCV78763DQ6 <u>A</u> R2G (Gresham and Fab2 +AMKOR P1 and OSPI)		
	<b>New Part Marking</b> : The fab will be identified by the first character of the date code. The character for Gresham is "G", for Fab 2 is "2".		
	NV78763-6 FAWL YYWWG		
	UUUUUUUUUUUUUUUUUUUUUUUUUUUU **********		
Change category:	Wafer Fab Change Assembly Change Test	t Change 🔲 Other	
Change Sub-Category(s):		<ul> <li>Datasheet/Product Doc change</li> <li>Shipping/Packaging/Marking</li> <li>Other: _New orderable part number</li> </ul>	
Sites Affected:	plicable ON Semiconductor site(s) : ON Gresham, Oregon	<ul> <li>External Foundry/Subcon site(s)</li> <li>Amkor Technology Philippines P1</li> </ul>	



## **Description and Purpose:**

Addition of ON Semiconductor Gresham, Oregon as wafer fab location (I3T80U technology), currently manufactured in Fab2, Oudenaarde, Belgium and addition of AMKOR P1, Philippines, as an assembly location, (36Id SSOP), currently manufactured in OSPI, Philippines, for NCV78763DQ6R2G. This will increase ON Semiconductor's wafer fab and assembly capacity and flexibility for this device.

For traceability, the dual-source version of the L763DQ6 device will get a new OPN (NCV78763DQ6<u>A</u>R2G) and a fab indicator (F) will be added in the front of the date code where this F will be"2" for Fab2 version and "G" for the Gresham version. Polyimide is also added to the Gresham fab version as part of our global quality continuous improvement program.

## **Qualification Plan:**

## Note: Qualification Plan is attached.

- To access file attachments on pdf copy of PCN, please be guided by the steps below:
- 1. Download pdf copy of the PCN to your computer
- 2. Open the downloaded pdf copy of the PCN
- 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
- 4. Then click on the attached file/s

## Estimated date for qualification completion: 31 August 2016

List of Affected Standard Parts:			
Current Part Number	Dual Source Part Number	Qualification Vehicle	
NCV78763DQ6R2G	NCV78763DQ6 <u>A</u> R2G	0L763-601 (L763_PBC Gresham)	